# **NDiS B560**





### Main Features

- Support 9th and 8th Gen Intel® Core™ i9/i7/i5/i3 LGA socket type embedded processor, up to 35W
- Intel® Q370
- Intel® integrated UHD 630 graphic engine
- Support 3 independent 4K2K 60Hz display output
- Support 1 x 2.5" SATA HDD

- 3 x HDMI 2.0, 6 x USB 3.0, 2 x GbE LAN, 4 x COM, 1 x Line-out, 1 x Mic-in
- Support M.2 Key B/E/M
- Fanless design
- Support extended temperature -20~60°C

### **Product Overview**

Powered by the 9th and 8th generation Intel® Core™ processor series and Intel® 300 Series chipset integrated graphics controller, the NDiS B560 fanless embedded system can handle powerful multimedia content. In addition, the NDiS B560 can be operated in an extended operating temperature range between -20 to 60 Celsius degree, with three 4K2K independent display output and rich connectives including Wi-Fi and 4G, 5G support, the NDiS B560 can fully satisfy customer's expectation and therefore be used in both in-door and out-door applications such as self-service KIOSK, vending machine, hospitality, and passenger information at outdoor bus station.

## **Specifications**

### **CPU Support**

- 9th and 8th Gen Intel® Core™ i9/i7/i5/i3 LGA socket type processor, up to 35W
  - Core™ i9-9900T, 8 Core, 2.1GHz, 16M Cache (0~40°C)
  - Core™ i7-9700TE, 8 Core, 1.8GHz, 12M Cache
  - Core™ i5-9500TE, 6 Core, 2.2GHz, 9M Cache
  - Core™ i3-9100TE, 4 Core, 2.2GHz, 6M Cache
  - Core<sup>™</sup> i7-8700T, 6 Core, 2.4GHz, 12M Cache - Core<sup>™</sup> i5-8500T, 6 Core, 2.1GHz, 9M Cache
  - Core™ i3-8100T, 4 Core, 3.1GHz, 6M Cache

### Chipset

• Intel® PCH Q370

### Graphics

• Intel® UHD graphics 630 series

### Main Memory

2 x 260-pin SO-DIMM sockets, support DDR4 2666 MHz non-ECC, unbuffered memory up to 32G (single socket max. 16GB)

### I/O Interface-Front

- 1 x Power button with LED
- 1 x Power LED, 1 x HDD LED

- 1 x Reset switch
- 2 x USB 3.0
- 4 x DB9 for COM1~ COM4
  - COM1: RS-232/422/485
  - COM2~4: RS232
- 2 x Antenna hole

### I/O Interface-Rear

- +12V DC-in
- 3 x HDMI 2.0
- 4 x USB 3.0
- 2 x RJ45 with LED for 10/100/1000Mbs
- 1 x Mic-in, 1 x Line-out
- 2 x Antenna hole

### I/O Interface-Internal

- 8CH GPIO support 4 x GPO and 4 x GPI
- Onboard TPM 2.0
- Support iAMT

### Storage

- 1 x SATA 2.5" HDD/SSD
- 1 x M.2 2280 (SATA, PCIe x4)/2242 (by request) Key M socket



# Dimension Drawing 238.00 238.00 388 6730

### Expansion

- 1 x M.2 2230 Key E (PCIe x2), support optional Wi-Fi modules
- 1 x M.2 3042/3052 Key B (SATA, USB 3.0), support optional 3G, 4G or 5G modules
- 1 x SIM slot

### **Power Supply**

- 1 x External 96W AC/DC power adapter
- Input: 100VAC to 240VAC
- Output: DC+12VDC

### Environment

- Operating temperature: -20°C to 60°C
- Storage temperature: -20°C to 80°C
- Humidity: 10 to 95% (non-condensing)

### Certification

- CE Approval
- FCC Class A

### Dimensions

• 238mm (W) x 192mm (D) x 67.29mm (H)

### **Operating System Support**

• Win10/Linux

# **Ordering Information**

• NDIS B560 (P/N: 10W00B56000X0)
9th and 8th Gen Intel® Core™ processor (up to 35W) fanless system
Intel® Q370 chipset

NE(COM